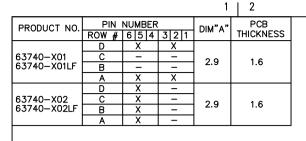
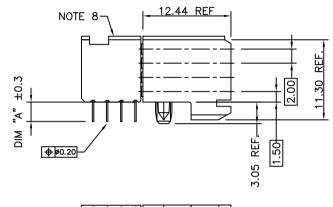
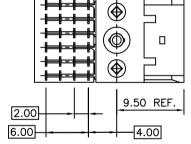


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11.95 REF.

① BODY MAT'L:LIQUID CRYSTAL POLYMER 30% GLASS FLAME RETARDANT ACC. UL 94-V0

TERMINAL MATERIAL: PHOSPHOR BRONZE.

INDICATED HOLES ARE UNPLATED.

NOTES:

4. PLATING OF COMPLIANT SECTION 0.5-1.5 µm SnPb 85-97 OR 0.5-1.5 µm PURE Sn FOR LEAD FREE

5. PRODUCT MARKING: PART NUMBER & BATCH ID.

(6.) SET BACK FOR PRESS BLOCK

7. SEE TA-941 FOR APPLICATION TOOLING

(8) TOP SURFACE OF PRESS BLOCK MAY EXTEND UP TO 0.4MM HIGHER THAN HOUSING. THIS MAY AFFECT THE TAIL LENGTH BEFORE APPLICATION TO A BOARD.

9 THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN 65-22-008. 10 THE HOUSING WILL WITHSTAND EXPOSURE TO 260DEGREE PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION.

RECOMMENDED HOLE PATTERN,

COMPONENT SIDE.

ma		. code NOTE 1 & 2				tolerances unless otherwise specified					CUSTOMER			F	CJ								
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SEE PRESS-FIT

HOLE CHART

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SEE NOTE 4.

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PRESS-FIT HOLES						
HOLE DIAMETER						
AFTER PLATING	0.65-0.80					
DRILLED HOLE	0.81-0.86					
COPPER PLATING	0.025 MIN.					
SnPb PLATING	0.005-0.015					
•						

PRODUCT #:	PLATING CONTACT AREA:	UNDERPLATING
63740-1YY	0.8 μm GOLD	1.3 μm Ni MIN.
63740-2YY	2.0 μm GOLD	1.3 μm Ni MIN.
63740-9YY	0.8 μm GXT	1.3 μm Ni MIN.
63740-1YYLF	0.8 m GOLD	1.3 m Ni MIN.
63740-2YYLF	2.0 m GOLD	1.3 m Ni MIN.
63740-9YYLF	0.8 m GXT	1.3 m Ni MIN.

22526 STATUS Released

Printed: Jul 201

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ACAD

PDM: Rev:F

## **Mouser Electronics**

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